

MAIL STOP AMENDMENT
PATENT
8007-1116

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takashi SUEYOSHI et al. Conf. 1846

Application No. 10/594,221 Group 1796

Filed September 25, 2006 Examiner R. Loewe

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED
PRODUCT THEREOF

AMENDMENT

Assistant Commissioner for Patents May 24, 2010
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Official Action mailed February 24, 2010, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.